

NSBC114EDXV6T1, NSBC114EDXV6T5

Dual Bias Resistor Transistors

NPN Silicon Surface Mount Transistors with Monolithic Bias Resistor Network

The BRT (Bias Resistor Transistor) contains a single transistor with a monolithic bias network consisting of two resistors; a series base resistor and a base-emitter resistor. These digital transistors are designed to replace a single device and its external resistor bias network. The BRT eliminates these individual components by integrating them into a single device. In the NSBC114EDXV6T1 series, two BRT devices are housed in the SOT-563 package which is ideal for low power surface mount applications where board space is at a premium.

Features

- Simplifies Circuit Design
- Reduces Board Space
- Reduces Component Count
- Lead-Free Solder Plating
- These are Pb-Free Devices
- NSV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable

MAXIMUM RATINGS

($T_A = 25^\circ\text{C}$ unless otherwise noted, common for Q_1 and Q_2)

Rating	Symbol	Value	Unit
Collector-Base Voltage	V_{CBO}	50	Vdc
Collector-Emitter Voltage	V_{CEO}	50	Vdc
Collector Current	I_C	100	mAdc

THERMAL CHARACTERISTICS

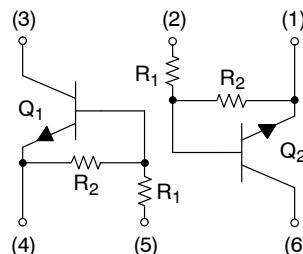
Characteristic (One Junction Heated)	Symbol	Max	Unit
Total Device Dissipation; $T_A = 25^\circ\text{C}$ Derate above 25°C	P_D	357 (Note 1) 2.9 (Note 1)	mW mW/ $^\circ\text{C}$
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	350 (Note 1)	$^\circ\text{C}/\text{W}$
Characteristic (Both Junctions Heated)	Symbol	Max	Unit
Total Device Dissipation; $T_A = 25^\circ\text{C}$ Derate above 25°C	P_D	500 (Note 1) 4.0 (Note 1)	mW mW/ $^\circ\text{C}$
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	250 (Note 1)	$^\circ\text{C}/\text{W}$
Junction and Storage Temperature Range	T_J, T_{stg}	-55 to +150	$^\circ\text{C}$

1. FR-4 @ Minimum Pad



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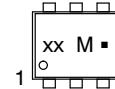


NSBC114EDXV6T1

MARKING DIAGRAM



SOT-563
CASE 463A



xx = Device Code (Refer to Page 2)
M = Date Code
■ = Pb-Free Package

ORDERING INFORMATION

Device	Package	Shipping [†]
NSBC1xxxDXV6T1	SOT-563	4000/Tape & Reel
NSBC1xxxDXV6T1G	SOT-563	4000/Tape & Reel
NSVBC1xxxDXV6T1G	SOT-563	4000/Tape & Reel
NSBC1xxxDXV6T5	SOT-563	8000/Tape & Reel
NSBC1xxxDXV6T5G	SOT-563	8000/Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

DEVICE MARKING INFORMATION

See specific marking information in the device marking table on page 2 of this data sheet.

NSBC114EDXV6T1, NSBC114EDXV6T5

DEVICE MARKING, ORDERING, AND RESISTOR VALUES

Device†	Package*	Marking	R1 (kΩ)	R2 (kΩ)
NSBC114EDXV6T1	SOT-563	7A	10	10
NSBC124EDXV6T1 / NSVBC124EDXV6T1G	SOT-563	7B	22	22
NSBC144EDXV6T1	SOT-563	7C	47	47
NSBC114YDXV6T1	SOT-563	7D	10	47
NSBC114TDXV6T1 (Note 2)	SOT-563	7E	10	∞
NSBC143TDXV6T1 (Notes 2)	SOT-563	7F	4.7	∞
NSBC113EDXV6T1 (Note 2)	SOT-563	7G	1.0	1.0
NSBC123EDXV6T1 (Notes 2)	SOT-563	7H	2.2	2.2
NSBC143EDXV6T1 (Notes 2)	SOT-563	7J	4.7	4.7
NSBC143ZDXV6T1 (Notes 2)	SOT-563	7K	4.7	47
NSBC124XDXV6T1 (Notes 2)	SOT-563	7L	22	47
NSBC123JDXV6T1 (Note 2)	SOT-563	7M	2.2	47
NSBC115EDXV6T1 (Notes 2)	SOT-563	7N	100	100
NSBC144WDXV6T1 (Notes 2)	SOT-563	7P	47	22

†The "G" suffix indicates Pb-Free package available.

*This package is inherently Pb-Free.

2. New resistor combinations. Updated curves to follow in subsequent data sheets.

ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted, common for Q_1 and Q_2)

Characteristic	Symbol	Min	Typ	Max	Unit
OFF CHARACTERISTICS					
Collector-Base Cutoff Current ($V_{CB} = 50 \text{ V}$, $I_E = 0$)	I_{CBO}	—	—	100	nAdc
Collector-Emitter Cutoff Current ($V_{CE} = 50 \text{ V}$, $I_B = 0$)	I_{CEO}	—	—	500	nAdc
Emitter-Base Cutoff Current ($V_{EB} = 6.0 \text{ V}$, $I_C = 0$)	I_{EBO}	—	—	0.5	mAdc
NSBC114EDXV6T1		—	—	0.2	
NSBC124EDXV6T1 / NSVBC124EDXV6T1G		—	—	0.1	
NSBC144EDXV6T1		—	—	0.2	
NSBC114YDXV6T1		—	—	0.9	
NSBC114TDXV6T1		—	—	1.9	
NSBC143TDXV6T1		—	—	4.3	
NSBC113EDXV6T1		—	—	2.3	
NSBC123EDXV6T1		—	—	1.5	
NSBC143EDXV6T1		—	—	0.18	
NSBC143ZDXV6T1		—	—	0.13	
NSBC124XDXV6T1		—	—	0.2	
NSBC123JDXV6T1		—	—	0.05	
NSBC115EDXV6T1		—	—	0.13	
NSBC144WDXV6T1		—	—		
Collector-Base Breakdown Voltage ($I_C = 10 \mu\text{A}$, $I_E = 0$)	$V_{(BR)CBO}$	50	—	—	Vdc
Collector-Emitter Breakdown Voltage (Note 3) ($I_C = 2.0 \text{ mA}$, $I_B = 0$)	$V_{(BR)CEO}$	50	—	—	Vdc

3. Pulse Test: Pulse Width < 300 μs , Duty Cycle < 2.0%

NSBC114EDXV6T1, NSBC114EDXV6T5

ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted, common for Q₁ and Q₂) (Continued)

Characteristic	Symbol	Min	Typ	Max	Unit
ON CHARACTERISTICS (Note 4)					
DC Current Gain ($V_{CE} = 10 \text{ V}$, $I_C = 5.0 \text{ mA}$)	h_{FE}	35	60	—	
		60	100	—	
		80	140	—	
		80	140	—	
		160	350	—	
		160	350	—	
		3.0	5.0	—	
		8.0	15	—	
		15	30	—	
		80	200	—	
		80	150	—	
		80	140	—	
		80	150	—	
		80	140	—	
Collector-Emitter Saturation Voltage ($I_C = 10 \text{ mA}$, $I_B = 0.3 \text{ mA}$) ($I_C = 10 \text{ mA}$, $I_B = 5 \text{ mA}$) ($I_C = 10 \text{ mA}$, $I_B = 1 \text{ mA}$)	$V_{CE(\text{sat})}$	—	—	0.25	Vdc
Output Voltage (on) ($V_{CC} = 5.0 \text{ V}$, $V_B = 2.5 \text{ V}$, $R_L = 1.0 \text{ k}\Omega$) NSBC114EDXV6T1 / NSVBC124EDXV6T1G NSBC114YDXV6T1 NSBC114TDXV6T1 NSBC143TDXV6T1 NSBC113EDXV6T1 NSBC123EDXV6T1 NSBC143ZDXV6T1 NSBC124XDXV6T1 NSBC123JDXV6T1 NSBC115EDXV6T1 NSBC144WDXV6T1	V_{OL}	—	—	0.2	Vdc
		—	—	0.2	
		—	—	0.2	
		—	—	0.2	
		—	—	0.2	
		—	—	0.2	
		—	—	0.2	
		—	—	0.2	
		—	—	0.2	
		—	—	0.2	
		—	—	0.2	
		—	—	0.2	
		—	—	0.2	
Output Voltage (off) ($V_{CC} = 5.0 \text{ V}$, $V_B = 0.5 \text{ V}$, $R_L = 1.0 \text{ k}\Omega$) ($V_{CC} = 5.0 \text{ V}$, $V_B = 0.050 \text{ V}$, $R_L = 1.0 \text{ k}\Omega$) ($V_{CC} = 5.0 \text{ V}$, $V_B = 0.25 \text{ V}$, $R_L = 1.0 \text{ k}\Omega$)	V_{OH}	4.9	—	—	Vdc
Input Resistor	R_1	7.0	10	13	k Ω
		15.4	22	28.6	
		32.9	47	61.1	
		7.0	10	13	
		7.0	10	13	
		3.3	4.7	6.1	
		0.7	1.0	1.3	
		1.5	2.2	2.9	
		3.3	4.7	6.1	
		3.3	4.7	6.1	
		15.4	22	28.6	
		1.54	2.2	2.86	
		70	100	130	
		32.9	47	61.1	
Resistor Ratio	R_1/R_2	0.8	1.0	1.2	
		0.17	0.21	0.25	
		—	—	—	
		0.8	1.0	1.2	
		0.055	0.1	0.185	
		0.38	0.47	0.56	
		0.038	0.047	0.056	
		1.7	2.1	2.6	

4. Pulse Test: Pulse Width < 300 μs , Duty Cycle < 2.0%

NSBC114EDXV6T1, NSBC114EDXV6T5

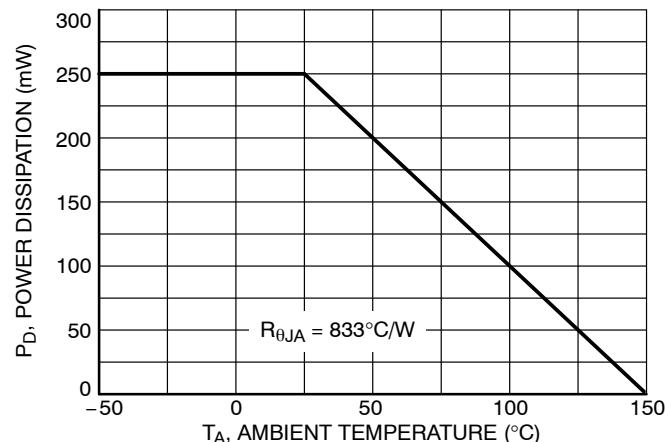


Figure 1. Derating Curve

NSBC114EDXV6T1, NSBC114EDXV6T5

TYPICAL ELECTRICAL CHARACTERISTICS — NSBC114EDXV6T1

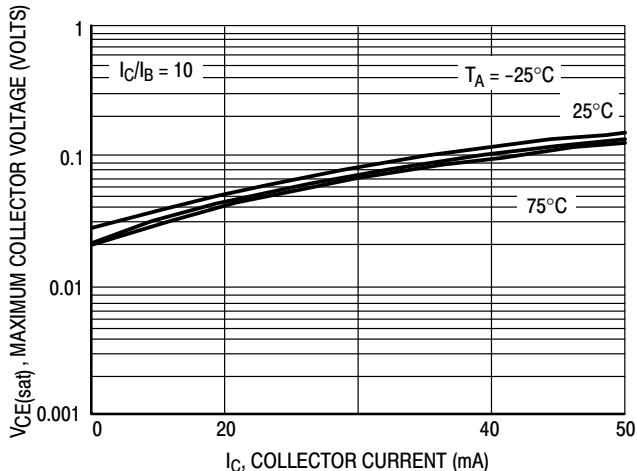


Figure 2. $V_{CE(sat)}$ versus I_C

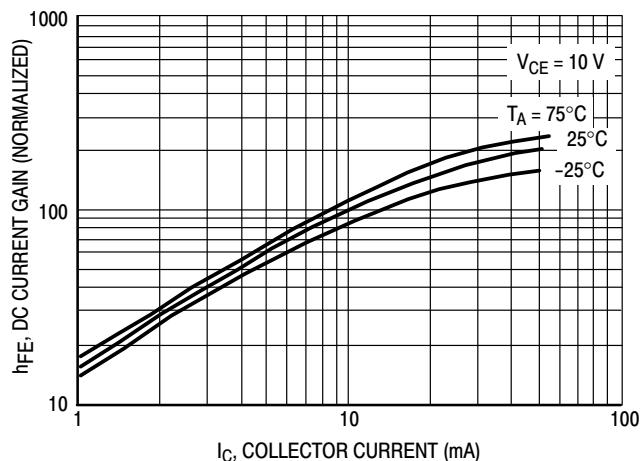


Figure 3. DC Current Gain

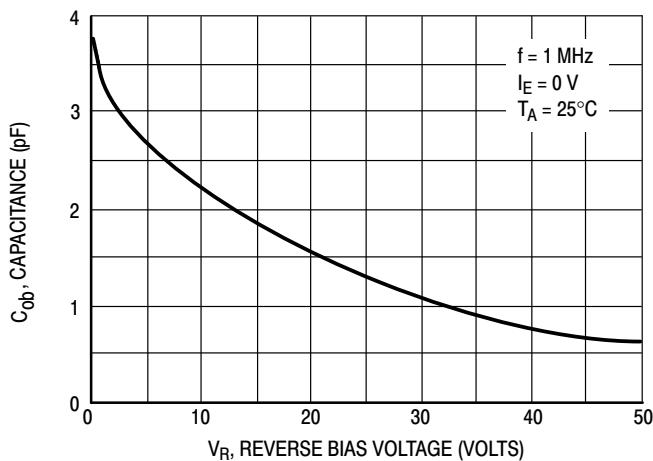


Figure 4. Output Capacitance

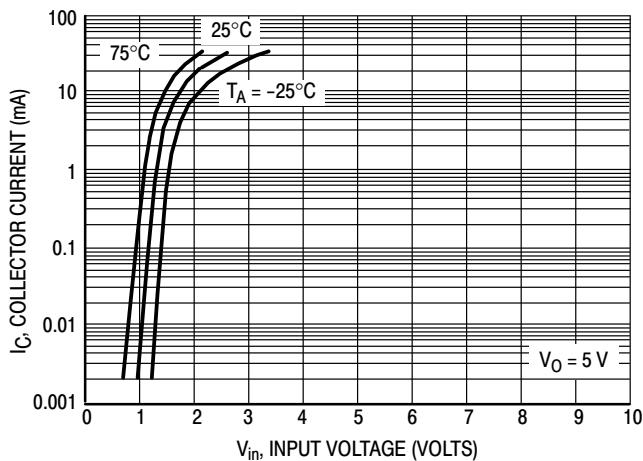


Figure 5. Output Current versus Input Voltage

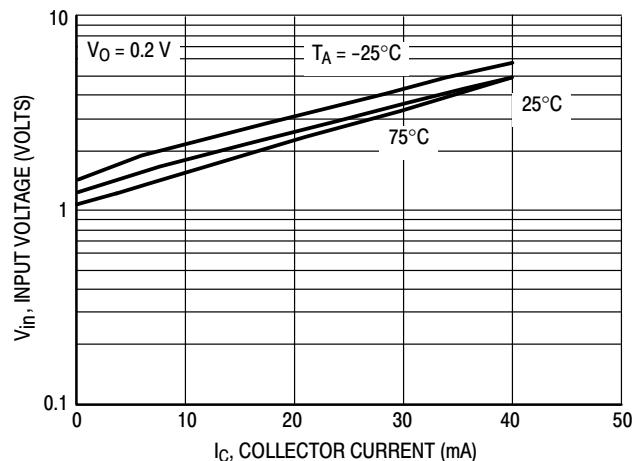


Figure 6. Input Voltage versus Output Current

NSBC114EDXV6T1, NSBC114EDXV6T5

TYPICAL ELECTRICAL CHARACTERISTICS — NSBC124EDXV6T1 / NSVBC124EDXV6T1G

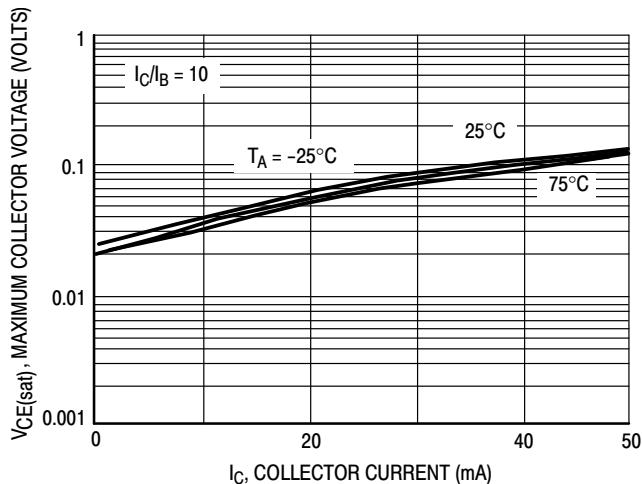


Figure 7. $V_{CE(sat)}$ versus I_C

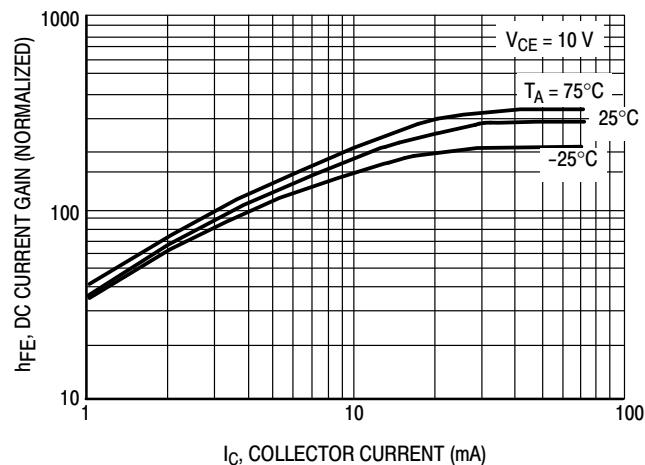


Figure 8. DC Current Gain

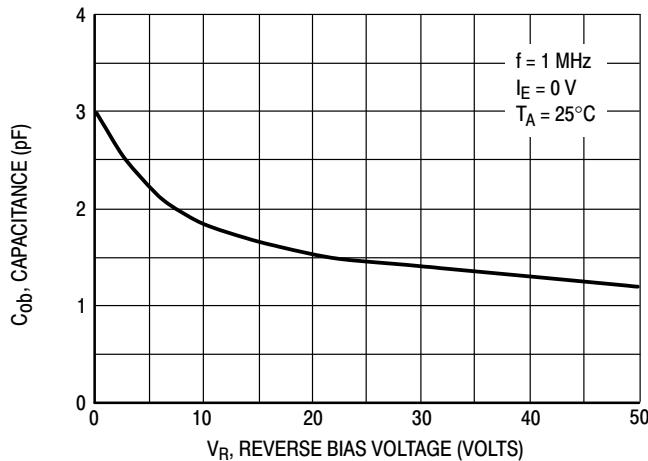


Figure 9. Output Capacitance

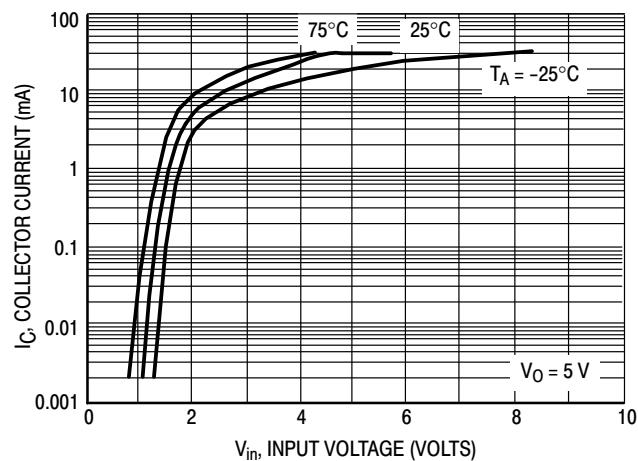


Figure 10. Output Current versus Input Voltage

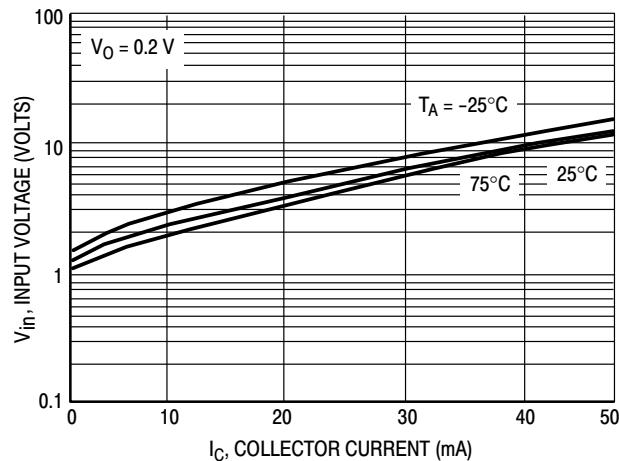


Figure 11. Input Voltage versus Output Current

NSBC114EDXV6T1, NSBC114EDXV6T5

TYPICAL ELECTRICAL CHARACTERISTICS — NSBC144EDXV6T1

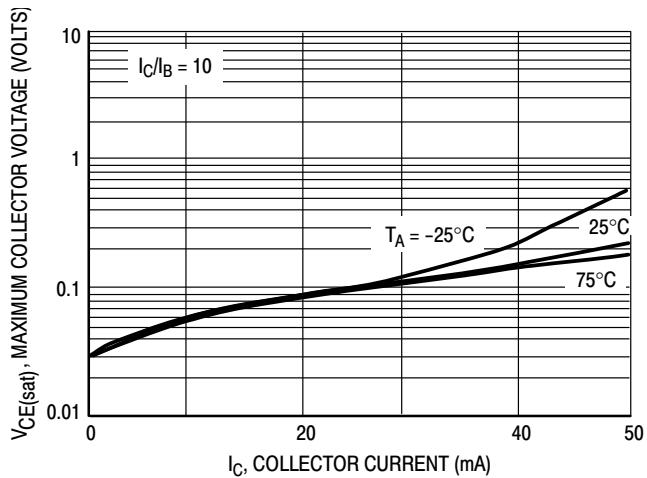


Figure 12. $V_{CE(\text{sat})}$ versus I_C

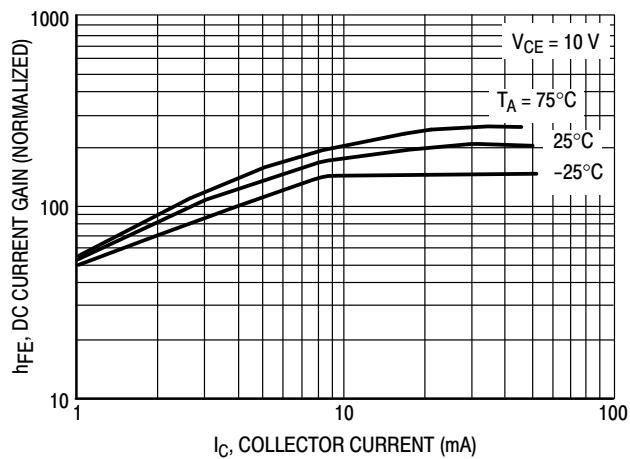


Figure 13. DC Current Gain

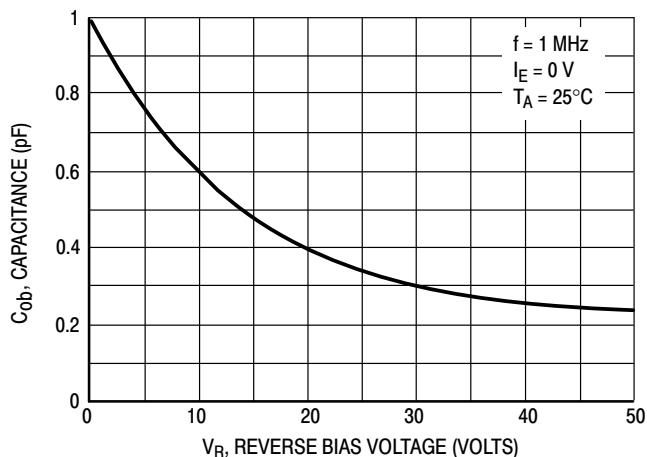


Figure 14. Output Capacitance

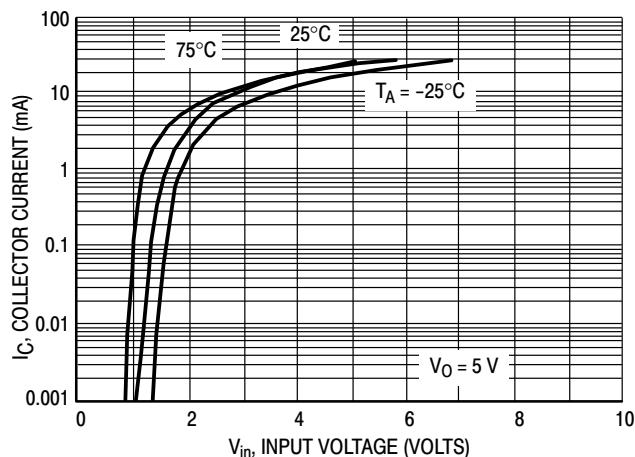


Figure 15. Output Current versus Input Voltage

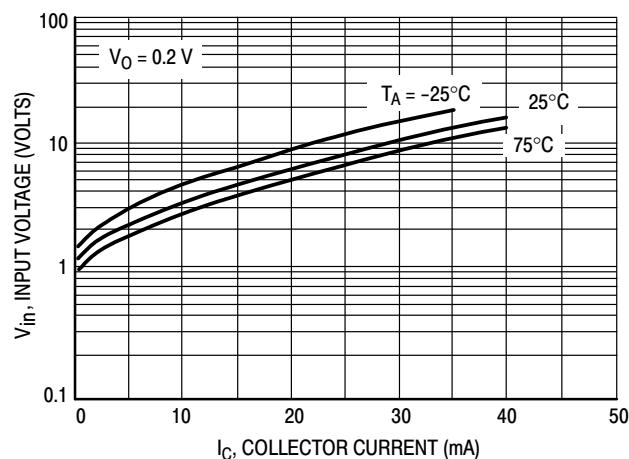


Figure 16. Input Voltage versus Output Current

NSBC114EDXV6T1, NSBC114EDXV6T5

TYPICAL ELECTRICAL CHARACTERISTICS — NSBC114YDXV6T1

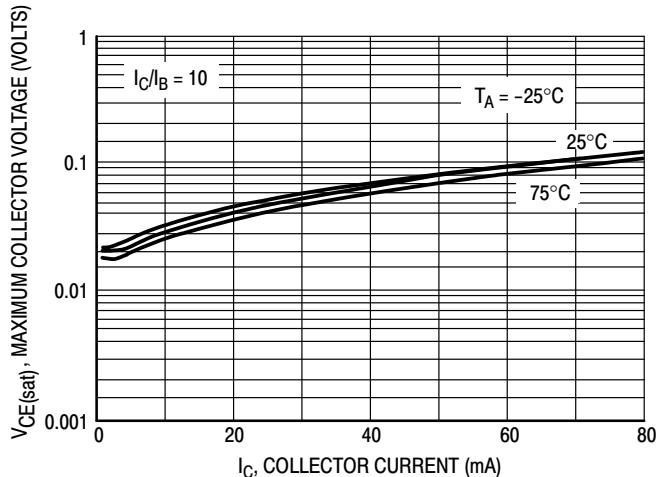


Figure 17. $V_{CE(\text{sat})}$ versus I_C

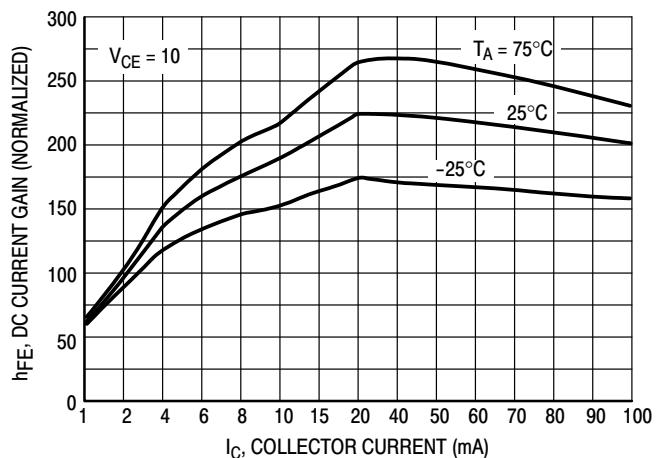


Figure 18. DC Current Gain

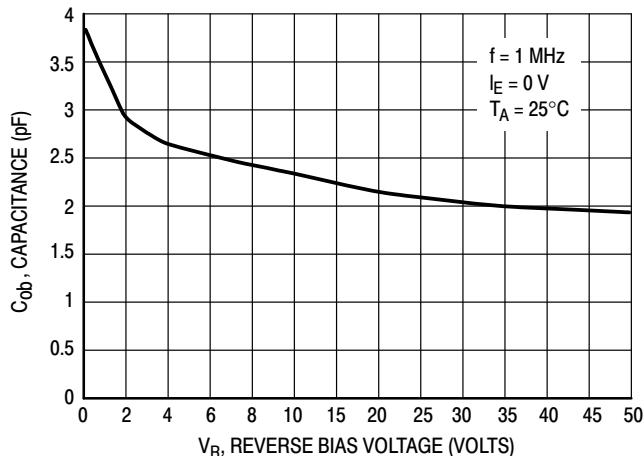


Figure 19. Output Capacitance

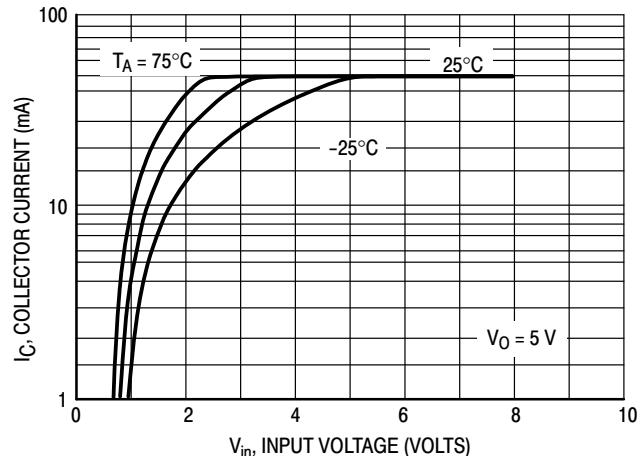


Figure 20. Output Current versus Input Voltage

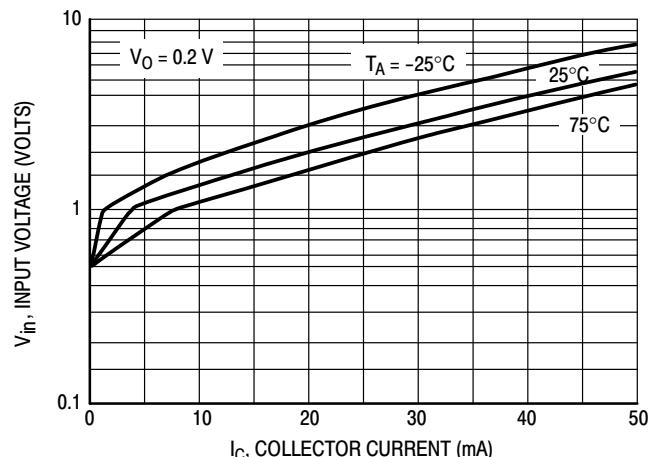


Figure 21. Input Voltage versus Output Current

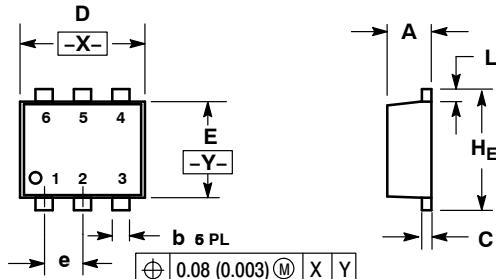
NSBC114EDXV6T1, NSBC114EDXV6T5

PACKAGE DIMENSIONS

SOT-563, 6 LEAD

CASE 463A

ISSUE F

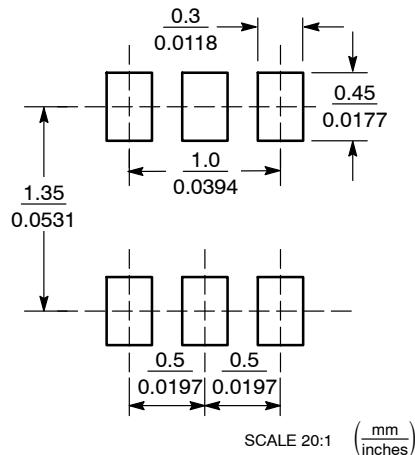


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETERS
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.50	0.55	0.60	0.020	0.021	0.023
b	0.17	0.22	0.27	0.007	0.009	0.011
C	0.08	0.12	0.18	0.003	0.005	0.007
D	1.50	1.60	1.70	0.059	0.062	0.066
E	1.10	1.20	1.30	0.043	0.047	0.051
e	0.5 BSC			0.02 BSC		
L	0.10	0.20	0.30	0.004	0.008	0.012
H_E	1.50	1.60	1.70	0.059	0.062	0.066

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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